APPLIED MATERIALS MIRRA CMP TOOL

AXUS TECHNOLOGY

Your source for leading-edge surface processing solutions

The Applied Materials Mirra CMP Tool is a Dry In - Wet Out (DI-WO) type of CMP machine which incorporates three polishing platens. The four wafer carriers are supported by a carousel transfer mechanism that moves the wafers through a one, two, or three step polishing process. It will process wafers from 150 to 200mm in diameter, and can be used for the planarization of thin films such as oxide, tungsten, and Polysilicon.

OPTIONAL CONFIGURATIONS
MIRRA TRAK - provides Dry In-Dry Out (DIDO) processing and is integrated with the OnTRAK "Integra" double sided wafer cleaning system.
MIRRA MESA - provides fully automated Dry In-Dry Out (DIDO) processing and is integrated with the MESA cleaner. A FABS unit is added that can accommodate up to four 25-wafer cassettes.
MIRRA DNS - integrated with the DNS AS-2000 Post-CMP cleaning tool and includes the FABS (Factory Automation Buffer Station) and an LTA (Linear Transfer Assembly).

FEATURES

- The Mirra's 4-head/3-platen architecture coupled with in-situ endpoint detection capability provides process flexibility and reliability.
- The Mirra system can be used alone or combined with a number of optional equipment to offer the process capability customers need.

For more information about refurbishment services, refurbished tools, or field services from Axus Technology, please contact Parts & Services or visit us at www.axustech.com.